



ALPHA & OMEGA
SEMICONDUCTOR

AON6816

30V Dual N-Channel AlphaMOS

General Description

- Latest Trench Power AlphaMOS (α MOS LV) technology
- Very Low RDS(on) at $4.5V_{GS}$
- Low Gate Charge
- ESD protection
- RoHS and Halogen-Free Compliant

Application

- DC/DC Converters

Product Summary

V_{DS}	30V
I_D (at $V_{GS}=10V$)	16A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	< 6.2m Ω
$R_{DS(ON)}$ (at $V_{GS} = 4.5V$)	< 9.6m Ω

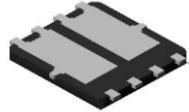
Typical ESD protection

- 100% UIS Tested
- 100% R_g Tested

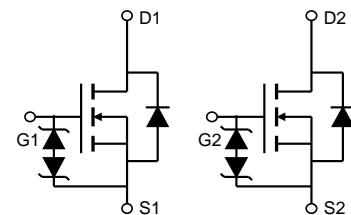
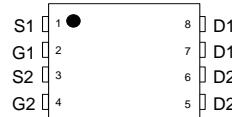
HBM Class 2



DFN5X6 EP2



Top View



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^G	I_D	16	A
$T_C=25^\circ C$		16	
$T_C=100^\circ C$			
Pulsed Drain Current ^C	I_{DM}	64	
Continuous Drain Current	I_{DSM}	16	A
$T_A=25^\circ C^G$		16	
$T_A=70^\circ C$		14	
Avalanche Current ^C	I_{AS}	35	A
Avalanche energy L=0.05mH ^C	E_{AS}	31	mJ
V_{DS} Spike	100ns	V_{SPIKE}	V
Power Dissipation ^B	P_D	21	W
$T_C=25^\circ C$		8	
$T_C=100^\circ C$			
Power Dissipation ^A	P_{DSM}	2.8	W
$T_A=25^\circ C$		1.8	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	35	45	°C/W
t ≤ 10s		65	80	°C/W
Maximum Junction-to-Ambient ^{A,D}	Steady-State			
Maximum Junction-to-Case	$R_{\theta JC}$	5	6	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			± 10	μA
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.2	1.8	2.2	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=16\text{A}$ $T_J=125^\circ\text{C}$	5	6.2	8.4	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=15\text{A}$	7.5	9.6		$\text{m}\Omega$
g_{fs}	Forward Transconductance	$V_{DS}=5\text{V}, I_D=16\text{A}$	62			S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$	0.7	1		V
I_{S}	Maximum Body-Diode Continuous Current ^G				16	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=15\text{V}, f=1\text{MHz}$		1540		pF
C_{oss}	Output Capacitance			485		pF
C_{rss}	Reverse Transfer Capacitance			448		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	0.8	1.7	2.6	Ω
SWITCHING PARAMETERS						
$\text{Q}_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, I_D=16\text{A}$		33.4	45	nC
$\text{Q}_g(4.5\text{V})$	Total Gate Charge			19.7	27	nC
Q_{gs}	Gate Source Charge			3.3		nC
Q_{gd}	Gate Drain Charge			15.0		nC
$t_{\text{D(on)}}$	Turn-On DelayTime	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, R_L=0.9\Omega, R_{\text{GEN}}=3\Omega$		7		ns
t_r	Turn-On Rise Time			8.3		ns
$t_{\text{D(off)}}$	Turn-Off DelayTime			24		ns
t_f	Turn-Off Fall Time			10		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=16\text{A}, dI/dt=500\text{A}/\mu\text{s}$		15.2		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=16\text{A}, dI/dt=500\text{A}/\mu\text{s}$		22.2		nC

A. The value of R_{DJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The Power dissipation P_{DSM} is based on R_{DJA} and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{C}$.

D. The R_{DJA} is the sum of the thermal impedance from junction to case R_{JJC} and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

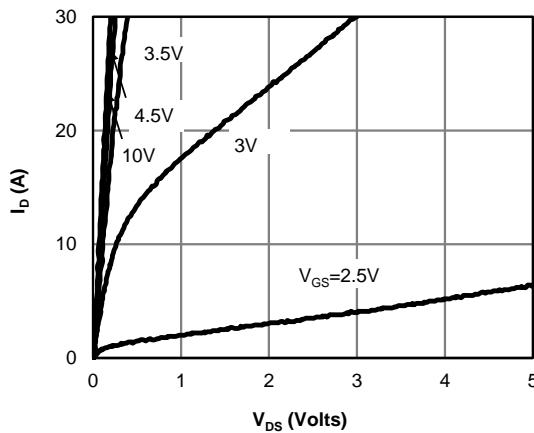
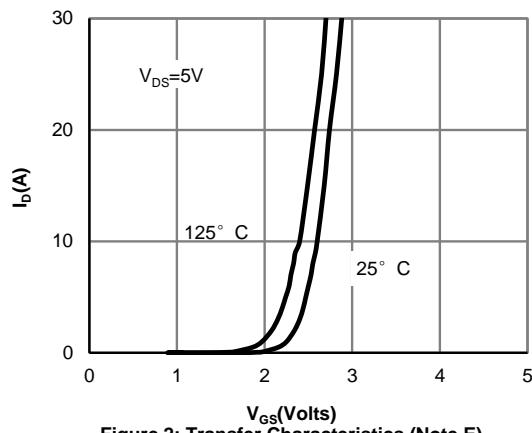
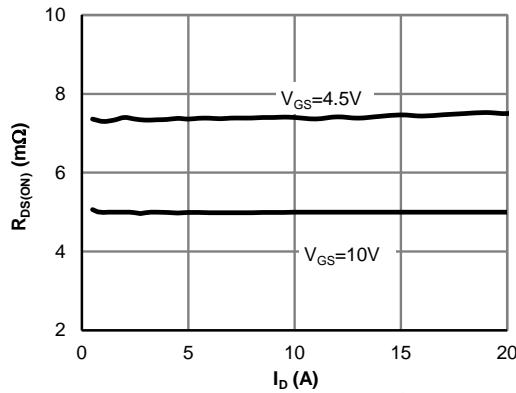
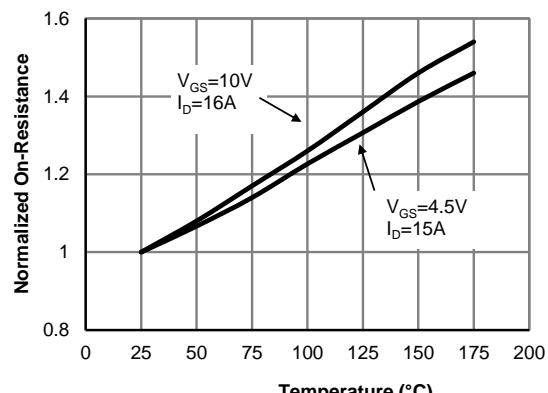
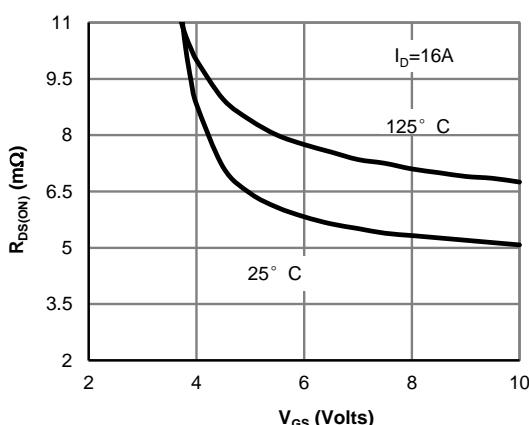
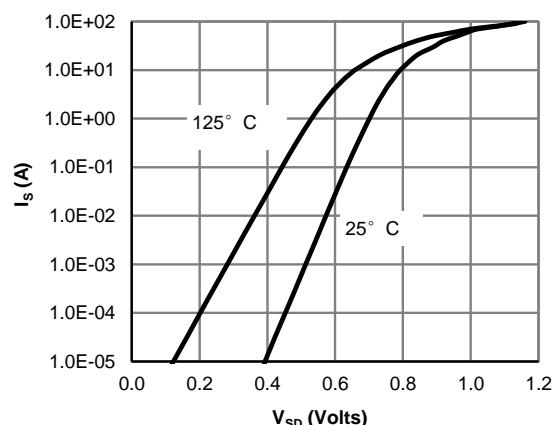
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(\text{MAX})}=150^\circ\text{C}$. The SOA curve provides a single pulse rating.

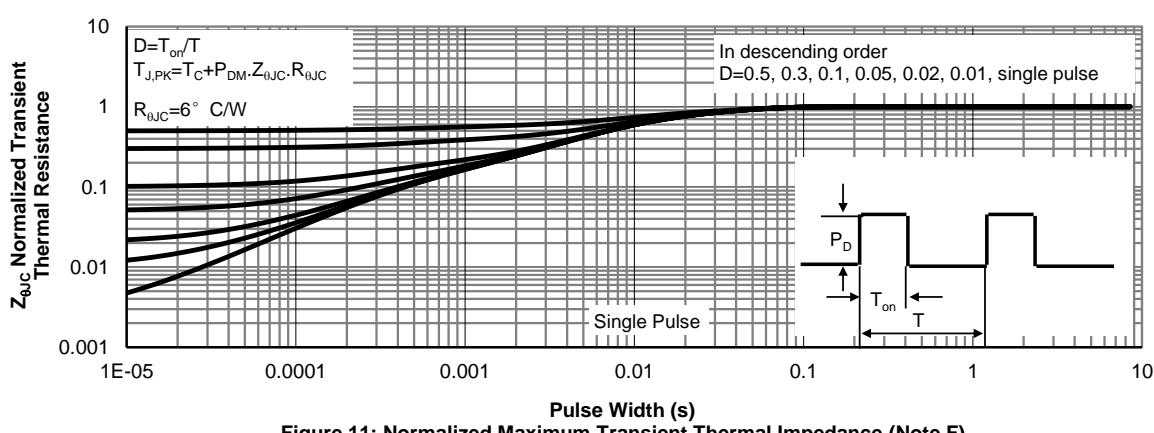
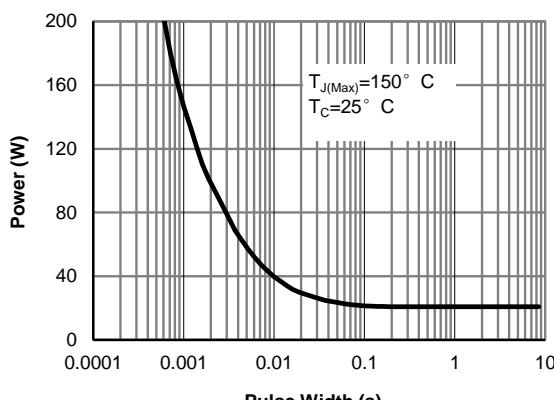
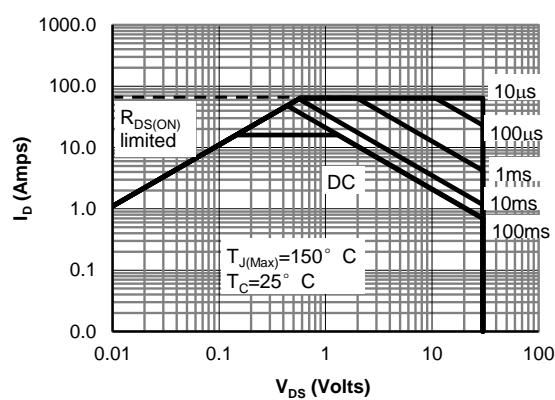
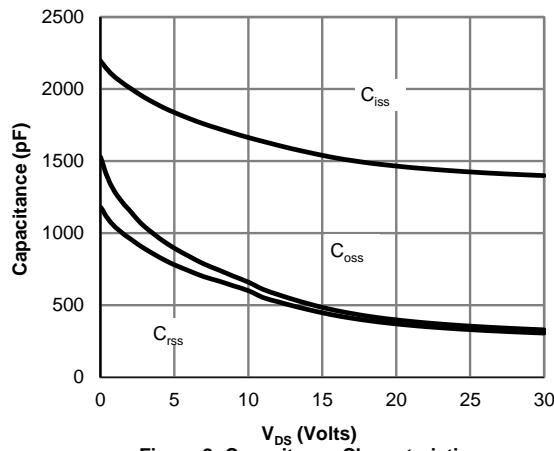
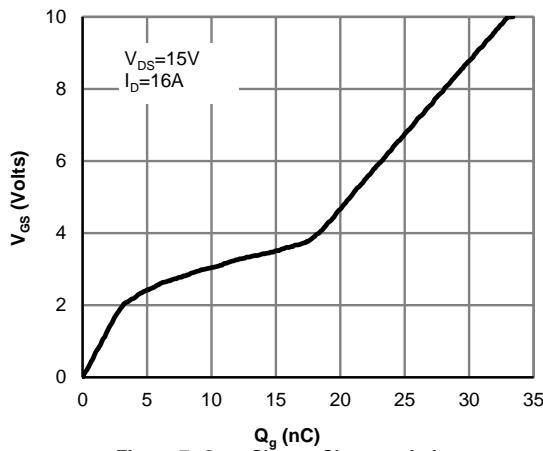
G. The maximum current rating is package limited.

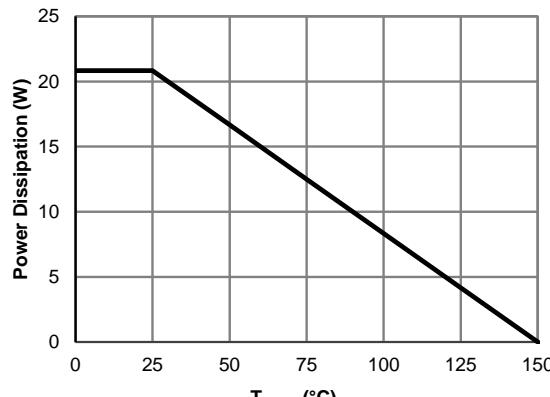
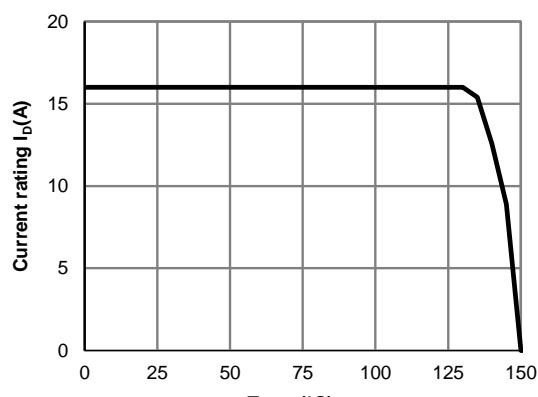
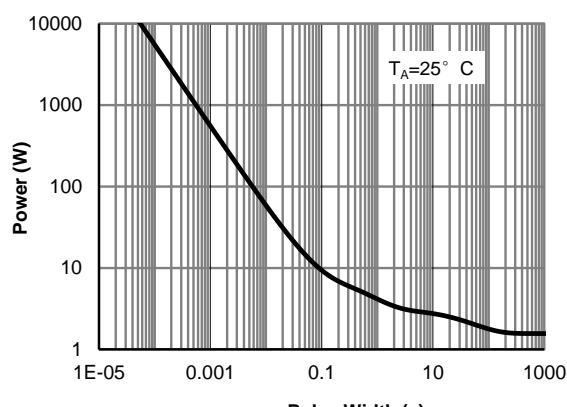
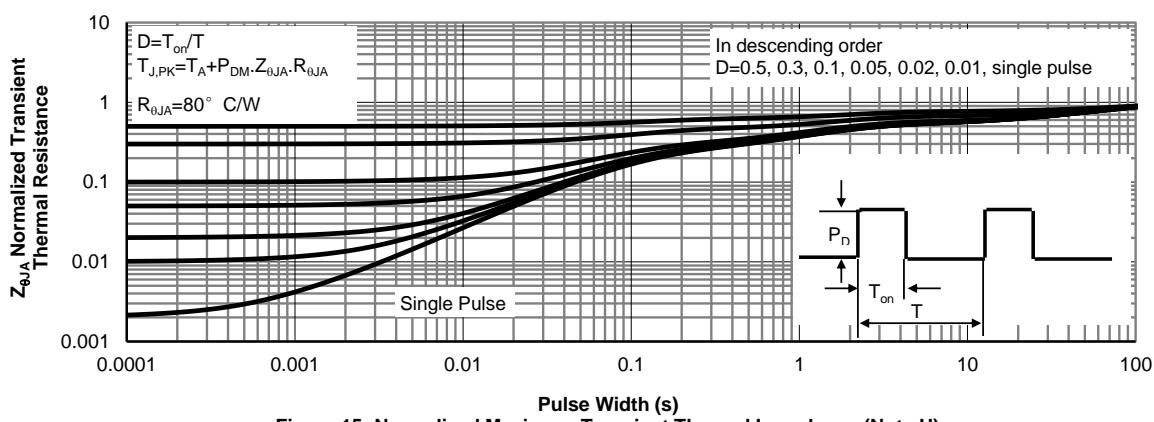
H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$.

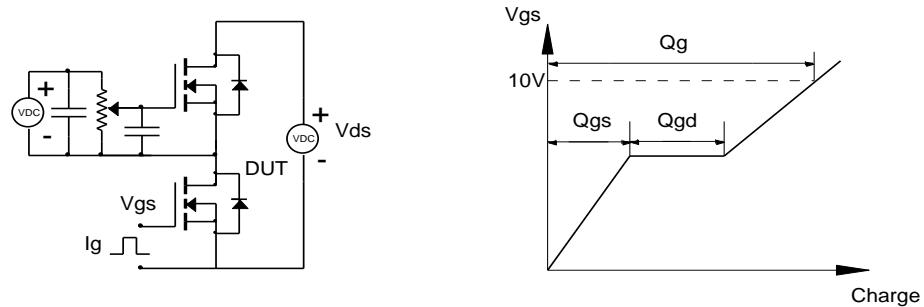
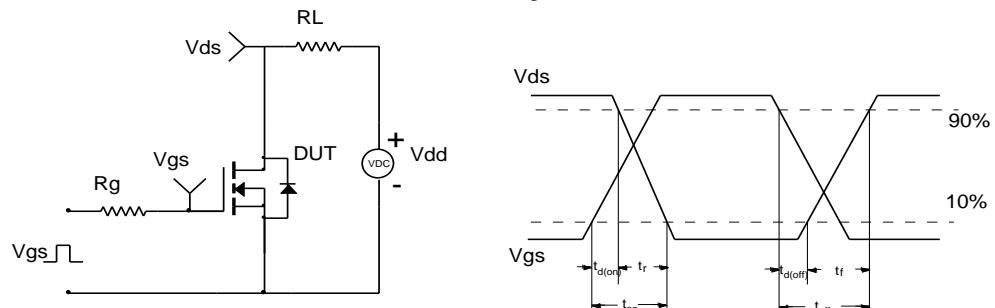
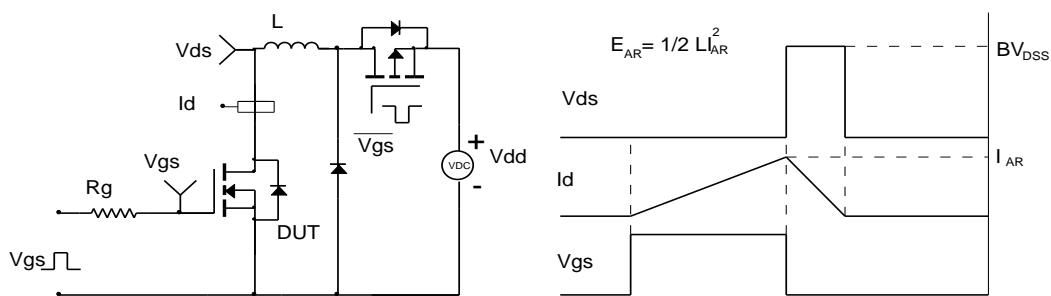
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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Fig 1: On-Region Characteristics (Note E)

Figure 2: Transfer Characteristics (Note E)

Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

Figure 4: On-Resistance vs. Junction Temperature (Note E)

Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS


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Figure 12: Power De-rating (Note F)

Figure 13: Current De-rating (Note F)

Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note H)

Figure 15: Normalized Maximum Transient Thermal Impedance (Note H)

Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

Diode Recovery Test Circuit & Waveforms
